

# 8216/8226 4-BIT PARALLEL BIDIRECTIONAL BUS DRIVER

- Data Bus Buffer Driver for 8080 CPU
- Low Input Load Current 0.25 mA Maximum
- High Output Drive Capability for Driving System Bus
- 3.65V Output High Voltage for Direct Interface to 8080 CPU
- 3-State Outputs
- Reduces System Package Count

The 8216/8226 is a 4-bit bidirectional bus driver/receiver. All inputs are low power TTL compatible. For driving MOS, the DO outputs provide a high 3.65V  $V_{OH}$ , and for high capacitance terminated bus structures, the DB outputs provide a high 50 mA  $I_{OL}$  capability. A non-inverting (8216) and an inverting (8226) are available to meet a wide variety of applications for buffering in microcomputer systems.

\*Note: The specifications for the 3216/3226 are identical with those for the 8216/8226.

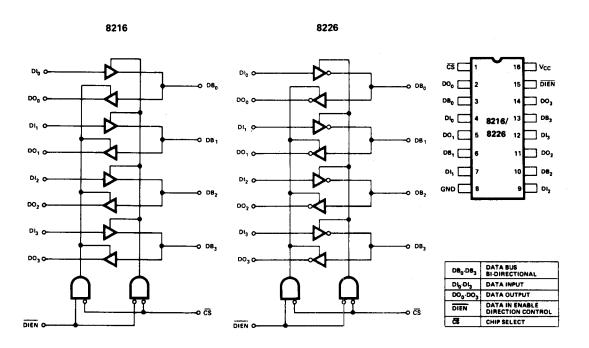


Figure 1. Block Diagrams

Figure 2. Pin Configuration



### **FUNCTIONAL DESCRIPTION**

Microprocessors like the 8080 are MOS devices and are generally capable of driving a single TTL load. The same is true for MOS memory devices. While this type of drive is sufficient in small systems with few components, quite often it is necessary to buffer the microprocessor and memories when adding components or expanding to a multi-board system.

The 8216/8226 is a four bit bi-directional bus driver specifically designed to buffer microcomputer system components.

#### **Bidirectional Driver**

Each buffered line of the four bit driver consists of two separate buffers that are tri-state in nature to achieve direct bus interface and bi-directional capability. On one side of the driver the output of one buffer and the input of another are tied together (DB), this side is used to interface to the system side components such as memories, I/O, etc., because its interface is direct TTL compatible and it has high drive (50mA). On the other side of the driver the inputs and outputs are separated to provide maximum flexibility. Of course, they can be tied together so that the driver can be used to buffer a true bi-directional bus such as the 8080 Data Bus. The DO outputs on this side of the driver have a special high voltage output drive capability (3.65V) so that direct interface to the 8080 and 8008 CPUs is achieved with an adequate amount of noise immunity (350mV worst case).

### Control Gating DIEN, CS

The  $\overline{CS}$  input is actually a device select. When it is "high" the output drivers are all forced to their high-impedance state. When it is at "zero" the device is selected (enabled) and the direction of the data flow is determined by the DIEN input.

The DIEN input controls the direction of data flow (see Figure 3) for complete truth table. This direction control is accomplished by forcing one of the pair of buffers into its high impedance state and allowing the other to transmit its data. A simple two gate circuit is used for this function.

The 8216/8226 is a device that will reduce component count in microcomputer systems and at the same time enhance noise immunity to assure reliable, high performance operation.

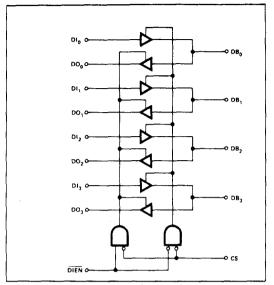


Figure 3a. 8216 Logic Diagram

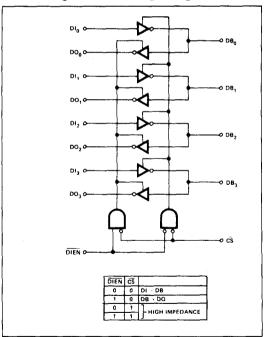


Figure 3b. 8226 Logic Diagram



### **ABSOLUTE MAXIMUM RATINGS\***

Temperature Under Bias 0°C to 70°C
Storage Temperature65°C to +150°C
All Output and Supply Voltages0.5V to +7V
All Input Voltages1.0V to +5.5V
Output Currents

\*NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## **D.C. CHARACTERISTICS** ( $T_A = 0$ °C to +70°C, $V_{CC} = +5V \pm 5$ %)

	Parameter			Limits			
Symbol			Min.	Тур.	Max.	Unit	Conditions
l <sub>F1</sub>	Input Load Current DIEN, CS			-0.15	5	mA	V <sub>F</sub> = 0.45
I <sub>F2</sub>	Input Load Current All	Other Inpu	ts	-0.08	25	mA	V <sub>F</sub> = 0.45
I <sub>R1</sub>	Input Leakage Current I	DIEN, CS			80	μΑ	V <sub>R</sub> = 5.25V
I <sub>R2</sub>	Input Leakage Current I	Ol Inputs			40	μΑ	V <sub>R</sub> = 5.25V
V <sub>C</sub>	Input Forward Voltage	Clamp			-1	V	I <sub>C</sub> = -5mA
VIL	Input "Low" Voltage				.95	V	
VIH	Input "High" Voltage		2.0			V	
lo	Output Leakage Current (3-State)		OO OB		20 100	μА	V <sub>O</sub> = 0.45V/5.25V
	Power Supply Current	8216		95	130	mA	
lcc		8226		85	120	mA	
V <sub>OL1</sub>	Output "Low" Voltage			0.3	.45	٧	DO Outputs I <sub>OL</sub> =15mA DB Outputs I <sub>OL</sub> =25mA
	Output "Low" Voltage	8216		0.5	.6	V	DB Outputs loL=55mA
V <sub>OL2</sub>		8226		0.5	.6	V	DB Outputs IOL=50mA
V <sub>OH1</sub>	Output "High" Voltage		3.65	4.0	†··	V	DO Outputs I <sub>OH</sub> = -1mA
V <sub>OH2</sub>	Output "High" Voltage		2.4	3.0		V	DB Outputs IOH = -10mA
los	Output Short Circuit Co	urrent	-15 -30	-35 -75	-65 -120	mA mA	DO Outputs V <sub>O</sub> ≅0V, DB Outputs V <sub>CC</sub> =5.0V

#### NOTE:

Typical values are for  $T_A = 25^{\circ} \, \text{C}$ ,  $V_{CC} = 5.0 \, \text{V}$ .



## **CAPACITANCE**<sup>[5]</sup> $(V_{BIAS} = 2.5V, V_{CC} = 5.0V, T_A = 25^{\circ}C, f = 1 \text{ MHz})$

			Limits			
Symbol	Parameter	Min.	Typ.[1]	Max.	Unit	
CIN	Input Capacitance		4	8	рF	
C <sub>OUT1</sub>	Output Capacitance		6	10	рF	
C <sub>OUT2</sub>	Output Capacitance	:	13	18	pF	

### A.C. CHARACTERISTICS $(T_A = 0^{\circ}C \text{ to } +70^{\circ}C, V_{CC} = +5V \pm 5\%)$

		Limits						
Symbol	Parameter		Min.	Тур.[1]	Max.	Unit	Conditions	
T <sub>PD1</sub>	Input to Output Delay	DO Outputs		15	25	ns	$C_L$ =30pF, R <sub>1</sub> =300Ω R <sub>2</sub> =600Ω	
T <sub>PD2</sub>	Input to Output Delay	DB Outputs 8216		19	30	ns	C <sub>L</sub> =300pF, R <sub>1</sub> =90Ω	
		8226		16	25	ns	$R_2 = 180\Omega$	
TE	Output Enable Time	8216		42	65	ns	(Note 2)	
		8226		36	54	ns	(Note 3)	
То	Output Disable Time		1	16	35	ns	(Note 4)	

#### NOTE:

input pulse amplitude of 2.5V.

Input rise and fall times of 5 ns between 1 and 2 volts.

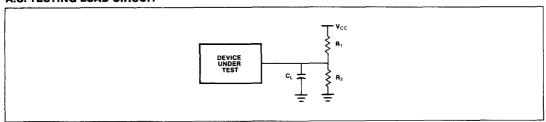
Output loading is 5 mA and 10 pF.

Speed measurements are made at 1.5 volt levels.

#### NOTES:

- 1. Typical values are for  $T_A = 25^{\circ}C$ ,  $V_{CC} \approx 5.0V$ .
- 2. DO Outputs, C<sub>L</sub> = 30pF, R<sub>1</sub> = 300/10 KΩ, R<sub>2</sub> = 180/1KΩ; DB Outputs, C<sub>L</sub> = 300pF, R<sub>1</sub> = 90/10 KΩ, R<sub>2</sub> = 180/1 KΩ.
- 3. DO Outputs, C<sub>L</sub> = 30pF, R<sub>1</sub> = 300/10 K $\Omega$ , R<sub>2</sub> = 600/1K; DB Outputs, C<sub>L</sub> = 300pF, R<sub>1</sub> = 90/10 K $\Omega$ , R<sub>2</sub> = 180/1 K $\Omega$ . 4. DO Outputs, C<sub>L</sub> = 5pF, R<sub>1</sub> = 300/10 K $\Omega$ , R<sub>2</sub> = 600/1 K $\Omega$ ; DB Outputs, C<sub>L</sub> = 5pF, R<sub>1</sub> = 90/10 K $\Omega$ , R<sub>2</sub> = 180/1 K $\Omega$ .
- 5. This parameter is periodically sampled and not 100% tested.

#### A.C. TESTING LOAD CIRCUIT



6-69 AFN-00733B



# **WAVEFORM**

